

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	24021	(circuit adj pattern\$2) with (chip or component or die or wafer or IC or (semiconductor adj device) or (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 16:54
L2	570	(electrode adj plate) with (electrode adj (finger\$2 or terminal\$2))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 16:56
L3	2	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 16:56
L4	33126	(electrode adj (finger\$2 or terminal\$2))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 17:17
L5	231	1 and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 16:56
L6	171	5 and (wire or wiring)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 17:18
L7	112	@ad <= "20030827" and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 17:18
L8	6442	1 and (lead or leadframe)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 17:18

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L9	2985	8 and (wire or wiring)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 17:25
L10	2102	@ad <= "20030827" and 9	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 17:25
L11	2473	257/784.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 17:19
L12	36	10 and 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 17:24
L13	7022	(power adj semiconductor adj device)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 17:25
L14	2147	13 and (wire or wiring)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 17:52
L15	1574	@ad <= "20030827" and 14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 17:52
L16	387940	"257"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 17:27

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L17	981	15 and 16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 17:49
L18	1	10/648,347	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 17:50
L19	908	257/672.ccls. or 257/673.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 17:52
L20	789	@ad <= "20030827" and 19	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 18:11
L21	614	20 and (wire or wiring)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 18:09
L22	371	21 and solder\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 18:09
L23	5096	257/666	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 18:05
L24	7932	((257/666) or (257/670) or (257/676) or (257/784) or (257/786) or (257/781) or (257/779) or (257/690-696)). CCLS.	USPAT	OR	OFF	2007/06/19 20:35

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L26	6398	24 and (wire or wiring)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:37
L27	4303	26 and solder\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:37
L28	2336	27 and terminal\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 18:10
L29	2149	28 and semiconductor\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:37
L30	1875	@ad <= "20030827" and 29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:33
L31	6182	source with (wiring or wire) with (pattern\$2 or trace\$2)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:32
L32	2741	drain with (wiring or wire) with (pattern\$2 or trace\$2)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:32
L33	2327	31 and 32	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:32

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L34	2095	33 and semiconductor\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:33
L35	1967	34 and electrode\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:38
L36	1323	@ad <= "20030827" and 35	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 22:18
L37	920	36 and 16	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:34
L38	916	37 not 30	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:34
L39	19	38 and (electrode adj terminal\$2)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:34
L40	2972	((257/666) or (257/670) or (257/676) or (257/784) or (257/786) or (257/781) or (257/779) or (257/690-696)). CCLS.	US-PGPUB	OR	OFF	2007/06/19 20:36
L42	2	40 and 35	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/06/19 20:36

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L43	2509	40 and (wire or wiring)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:37
L44	1757	43 and solder\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:37
L45	1595	44 and semiconductor\$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:37
L46	692	@ad <= "20030827" and 45	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:37
L47	692	46 not 30	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 20:37
L48	625	47 and (electrode\$2 or lead)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 22:11
L49	208202	electrode with (chip die component IC (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 22:15
L50	342132	(chip die component IC (integrated adj circuit)) with (trace\$2 or pattern\$2 or conductor\$2)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 22:17

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L51	37852	49 and 50	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 22:15
L52	4088	(electrode adj terminal\$2) with (chip die component IC (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 22:16
L53	1229	51 and 52	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 22:17
L54	72117	(trace\$2 or pattern\$2 or conductor\$2) with solder\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 22:17
L55	364	53 and 54	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 22:17
L56	275	55 and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 22:17
L57	188	@ad <= "20030827" and 56	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/19 22:19